

LOW LEAKAGE CIRCUIT BOARD FOR PROBE CARD AND LOW LEAKAGE PROBE CARD, AND FABRICATION METHOD OF SAME

ABSTRACT OF THE DISCLOSURE

A method of fabricating a circuit board for probe card by stacking from the bottom toward the top a support layer, an insulating layer and a conducting layer in a stack in which the support layer is prepared from a non-deformable and high hardness material, the insulating layer has a shape and size approximately equal to the support layer and a plurality of grooves thereon subject to a predetermined depth and pattern, and the conducting layer comprises a plurality of conducting strips respectively bonded to the top protruding portions of the insulating layer and electrically insulated from each other by the grooves.

Figure 1